



XENON Automatisierungstechnik GmbH 20th of February 2012

### **3D MID - Introduction**





#### 3D-MID

- > 3D-MID...**M**olded Interconnected **D**evices
- Combination of electrical, mechanical, fluidical and optical functions
- Plastic housing is becoming a printed circuit board

### Advantages of 3D-MID, e.g.

- > 3D design flexibility
- Miniaturization



**XENON competence**Production of process modules for the total MID value chain



### **Production line for 3D-MID Combi Switches**



Production line for 3D-MID combi switches



- > New transfer system with manipulable work piece carriers
- > 6-axis-industrial robots controlled by 3D vision systems
- Software based change over by host computer, one-piece-flow functionality
- > Product data logging with part-tracking (DMX-Code)







Versions of combi switches



### 3D-MID – Automation of the entire process chain



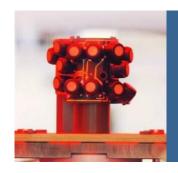
➤ Quality check of incoming parts (check of the metallization)



➤ Placement of SMD- and special components



➤ Insertion of contact pins (integrated connector)



- ➤ AOI of soldered MID parts
- ➤ Check presence of components



➤ Dispensing of soldering paste with subsequent optical inspection



- ➤ Electrical final test
- ➤ Mechanical final test



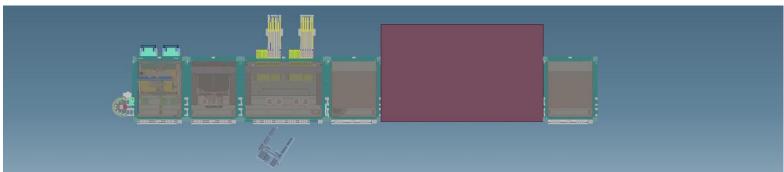
## **Production line – technical data**

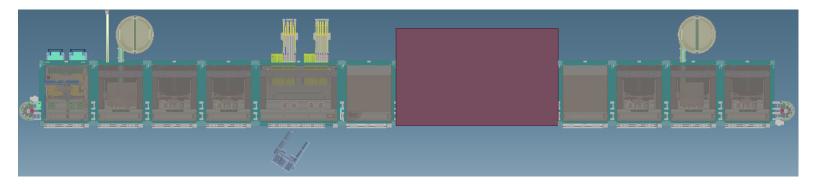
| Maximum MID size       | • 100 x 100 x 100 mm, full 3D-functionality up to 270°  |
|------------------------|---|
| Transport system       | <ul> <li>workpiece carrier transfer system with integrated</li> <li>workpiece positioning module</li> </ul>   |
| System repeat accuracy | • ±0,05 mm (6-axis robot) ±0,01 mm (linear directly driven gantry-system)   |
| Pad size               | • ca. 0,5 mm x 0,9 mm   |
| Dispense volume        | • ca. 0,06 mm³ to 1,2 mm³   |
| Dispense rate          | • 80 120 dots/min   |
| Component spectrum     | <ul> <li>SMD-Components: capsuled and non-capsuled active components;<br/>special components, power-LED, switches, switch-keys;<br/>contact pins</li> </ul> |
| Measurement technology | optical 3D-measuring system incl. distance measurement  |
| Measuring accuracy     | • lateral ±2,5 μm / vertical ±10μm  |

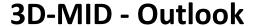


# 3D-MID – Scalable, modular production lines











### Breakthrough of the MID-technology, e.g.

- > Automotive
- > Telecommunication
- Medical Technology

### Advantages of the breakthrough of MID-technology, e.g.

- New areas of application by the use of optimized process technologies and materials
- > Dynamic development of the technique for production lines
- > Higher cost-effectiveness because of scaling effects





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